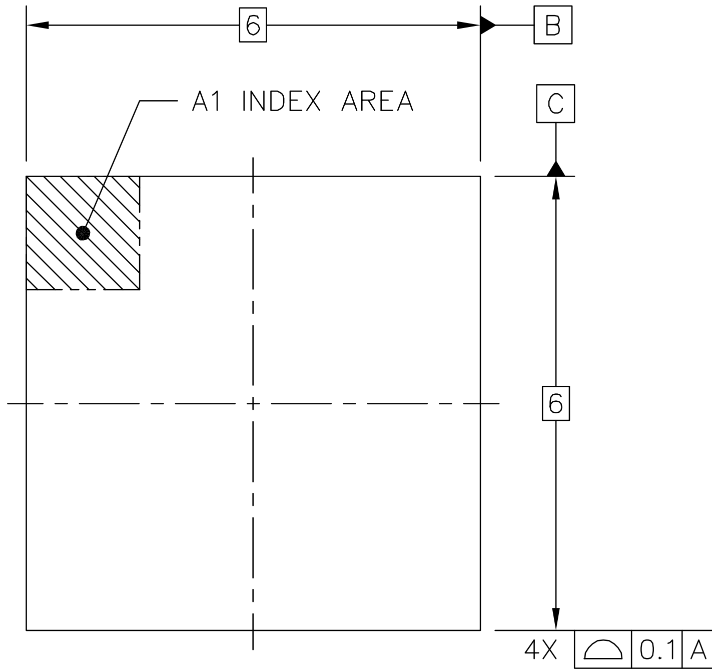
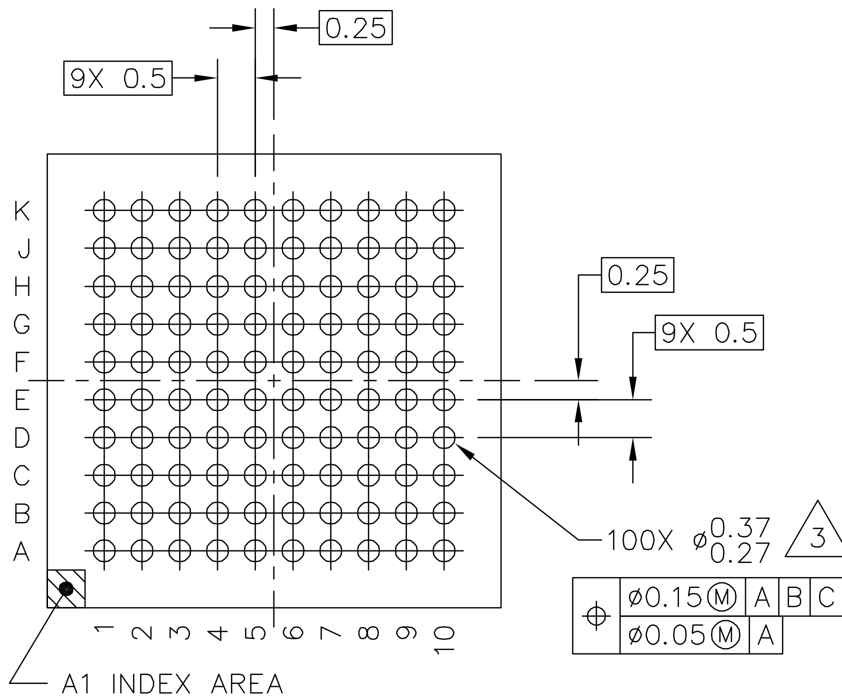
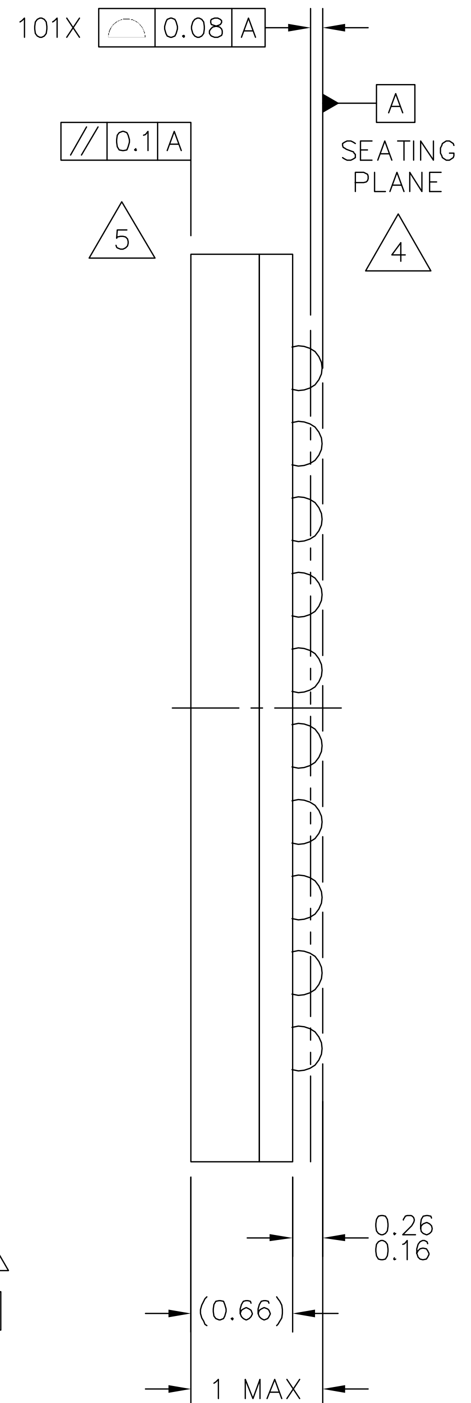


TOP VIEW



BOTTOM VIEW



SIDE VIEW

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TITLE: PBGA, VERY THIN PROFILE, FINE PITCH, 100 I/O, 6 X 6 PKG, 0.5 MM PITCH (MAP)	DOCUMENT NO: 98ARE10746D REV: B
	STANDARD: NON-JEDEC
	SOT1087-2 03 FEB 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. (△) MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. (△) DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. (△) PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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	SOT1087-2	03 FEB 2016